PIN 1 REFERENCE



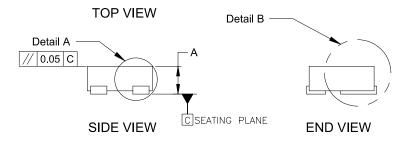
XDFNW3 1.00x1.00x0.38 0.65P CASE 521AC ISSUE B

DATE 07 MAY 2024

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS

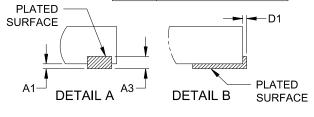
	MILLIMETERS			
DIM	MIN.	NOM.	MAX.	
Α	0.32	0.38	0.44	
A1	0.00		0.04	
A3	0.125 REF			
b	0.20	0.25	0.30	
D	0.90	1.00	1.10	
D1	0.00		0.04	
D2	0.75	0.80	0.85	
E	0.90	1.00	1.10	
E2	0.40	0.45	0.50	
е	0.65 BSC			
L	0.465	0.515	0.565	
K	0.23 REF			

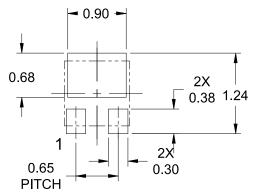


Α

В

1 2 b 0.05
BOTTOM VIEW





GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*

 For additional information on our Pb-Free strategy and soldering details, please download the ONSEMI Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DESCRIPTION: XDFNW3 1.00x1.00x0.38 0.65P		PAGE 1 OF 1

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